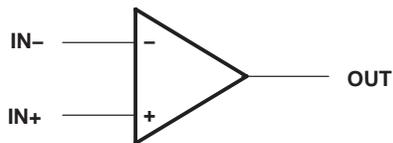


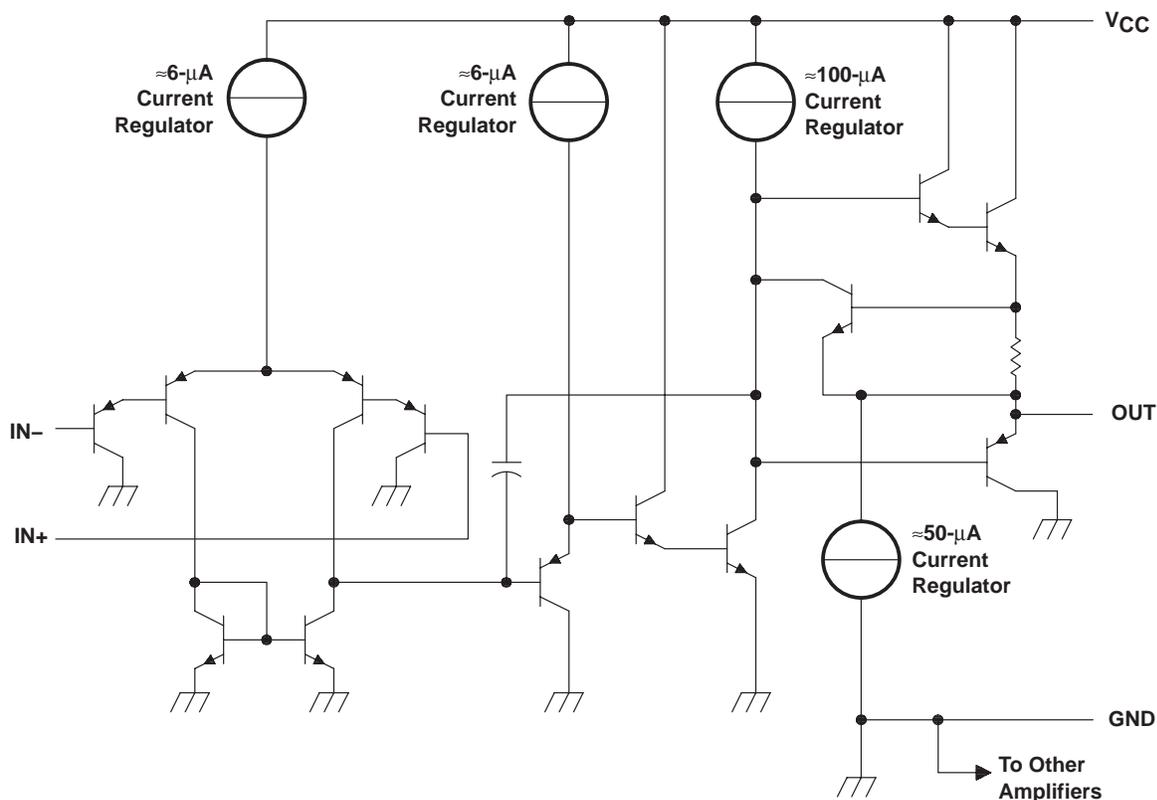
LM2902-Q1 QUADRUPLE OPERATIONAL AMPLIFIER

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symbol (each amplifier)



schematic (each amplifier)



COMPONENT COUNT (TOTAL DEVICE)	
Epi-FET	1
Transistors	95
Diodes	4
Resistors	11
Capacitors	4

LM2902-Q1 QUADRUPLE OPERATIONAL AMPLIFIER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	LM2902-Q1	LM2902KV-Q1	UNIT
Supply voltage, V_{CC} (see Note 1)	26	32	V
Differential input voltage, V_{ID} (see Note 2)	± 26	± 32	V
Input voltage, V_I (either input)	-0.3 to 26	-0.3 to 32	V
Duration of output short circuit (one amplifier) to ground at (or below) $T_A = 25^\circ\text{C}$, $V_{CC} \leq 15\text{ V}$ (see Note 3)	Unlimited	Unlimited	
Package thermal impedance, θ_{JA} (see Notes 4 and 5)	D package (0 LFPM)	101	$^\circ\text{C/W}$
	PW package	113	
Operating virtual junction temperature, T_J	142	142	$^\circ\text{C}$
Storage temperature range, T_{stg}	-65 to 150	-65 to 150	$^\circ\text{C}$

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages and V_{CC} specified for the measurement of I_{OS} , are with respect to the network GND.
 2. Differential voltages are at $IN+$ with respect to $IN-$.
 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 4. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 142°C can affect reliability.
 5. The package thermal impedance is calculated in accordance with JESD 51-7.



LM2902-Q1

QUADRUPLE OPERATIONAL AMPLIFIER

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electrical characteristics at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	T_A ‡	LM2902-Q1			UNIT
			MIN	TYP§	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to } 26\text{ V}$, $V_{IC} = V_{ICRmin}$, $V_O = 1.4\text{ V}$	25°C	3	7		mV
		Full range			10	
I_{IO} Input offset current	$V_O = 1.4\text{ V}$	25°C	2	50		nA
		Full range			300	
I_{IB} Input bias current	$V_O = 1.4\text{ V}$	25°C	-20	-250		nA
		Full range			-500	
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V to } 26\text{ V}$	25°C	0 to $V_{CC} - 1.5$			V
		Full range	0 to $V_{CC} - 2$			
V_{OH} High-level output voltage	$R_L = 10\text{ k}\Omega$	25°C	$V_{CC} - 1.5$			V
	$V_{CC} = 26\text{ V}$, $R_L = 2\text{ k}\Omega$	Full range	22			
	$V_{CC} = 26\text{ V}$, $R_L \geq 10\text{ k}\Omega$	Full range	23	24		
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$	Full range	5	20		mV
AVD Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1\text{ V to } 11\text{ V}$, $R_L \geq 2\text{ k}\Omega$	25°C	100			V/mV
		Full range	15			
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C	50	80		dB
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)		25°C	50	100		dB
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to } 20\text{ kHz}$	25°C	120			dB
I_O Output current	$V_{CC} = 15\text{ V}$, $V_{ID} = 1\text{ V}$, $V_O = 0$	25°C	-20	-30	-60	mA
		Full range	-10			
	$V_{CC} = 15\text{ V}$, $V_{ID} = -1\text{ V}$, $V_O = 15\text{ V}$	25°C	10	20		
		Full range	5			
I_{OS} Short-circuit output current	V_{CC} at 5 V, $V_O = 0$, GND at -5 V	25°C	±40	±60		mA
		Full range	0.7 1.2			
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V}$, No load	Full range	0.7	1.2		mA
	$V_{CC} = 26\text{ V}$ $V_O = 0.5 V_{CC}$, No load	Full range	1.4	3		

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

‡ Full range is -40°C to 125°C.

§ All typical values are at $T_A = 25^\circ\text{C}$.



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electrical characteristics at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)
(continued)

PARAMETER	TEST CONDITIONS†		T_A ‡	LM2902KV-Q1			UNIT
				MIN	TYP§	MAX	
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to }32\text{ V}$, $V_{IC} = V_{ICRmin}$, $V_O = 1.4\text{ V}$	Non-A devices	25°C	3	7	mV	
			Full range	10			
		A-suffix devices	25°C	1	2		
			Full range	4			
$\Delta V_{IO}/\Delta T$ Temperature drift	$R_S = 0\ \Omega$	Full range	7		$\mu\text{V}/^\circ\text{C}$		
I_{IO} Input offset current	$V_O = 1.4\text{ V}$	25°C	2	50	nA		
		Full range	150				
$\Delta I_{IO}/\Delta T$ Temperature drift		Full range	10		$\text{pA}/^\circ\text{C}$		
I_{IB} Input bias current	$V_O = 1.4\text{ V}$	25°C	-20	-250	nA		
		Full range	-500				
V_{ICR} Common-mode input voltage range	$V_{CC} = 5\text{ V to }32\text{ V}$	25°C	0 to $V_{CC} - 1.5$		V		
		Full range	0 to $V_{CC} - 2$				
V_{OH} High-level output voltage	$R_L = 10\text{ k}\Omega$	25°C	$V_{CC} - 1.5$		V		
	$V_{CC} = 32\text{ V}$, $R_L = 2\text{ k}\Omega$	Full range	26				
	$V_{CC} = 32\text{ V}$, $R_L \geq 10\text{ k}\Omega$	Full range	27				
V_{OL} Low-level output voltage	$R_L \leq 10\text{ k}\Omega$	Full range	5	20	mV		
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1\text{ V to }11\text{ V}$, $R_L \geq 2\text{ k}\Omega$	25°C	25	100	V/mV		
		Full range	15				
Amplifier-to-amplifier coupling¶	$f = 1\text{ kHz to }20\text{ kHz}$, input referred	25°C	120		dB		
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICRmin}$	25°C	60	80	dB		
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$)		25°C	60	100	dB		
V_{O1}/V_{O2} Crosstalk attenuation	$f = 1\text{ kHz to }20\text{ kHz}$	25°C	120		dB		
I_O Output current	$V_{CC} = 15$ $V_O = 0$	$V_{ID} = 1\text{ V}$,	25°C	-20	-30	-60	mA
			Full range	-10			
	$V_{CC} = 15$ $V_O = 15\text{ V}$	$V_{ID} = -1\text{ V}$,	25°C	10	20		
			Full range	5			
	$V_{ID} = -1\text{ V}$, $V_O = 200\text{ mV}$	25°C	12	40	μA		
I_{OS} Short-circuit output current	V_{CC} at 5 V, GND at -5 V	$V_O = 0$,	25°C	± 40	± 60	mA	
I_{CC} Supply current (four amplifiers)	$V_O = 2.5\text{ V}$, No load		Full range	0.7	1.2	mA	
	$V_{CC} = 32\text{ V}$ $V_O = 0.5 V_{CC}$, No load		Full range	1.4	3		

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.

‡ Full range is -40°C to 125°C .

§ All typical values are at $T_A = 25^\circ\text{C}$.

¶ Due to proximity of external components, ensure that coupling is not originating via stray capacitance between these external parts. Typically, this can be detected, as this type of coupling increases at higher frequencies.



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operating conditions, $V_{CC} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	$R_L = 1\text{ M}\Omega$, $C_L = 30\text{ pF}$, $V_I = \pm 10\text{ V}$ (see Figure 1)	0.5	$\text{V}/\mu\text{s}$
B_1	Unity-gain bandwidth	$R_L = 1\text{ M}\Omega$, $C_L = 20\text{ pF}$ (see Figure 1)	1.2	MHz
V_n	Equivalent input noise voltage	$R_S = 100\ \Omega$, $V_I = 0\text{ V}$, $f = 1\text{ kHz}$ (see Figure 2)	35	$\text{nV}/\sqrt{\text{Hz}}$

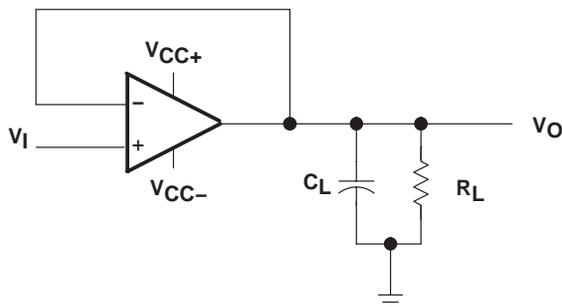


Figure 1. Unity-Gain Amplifier

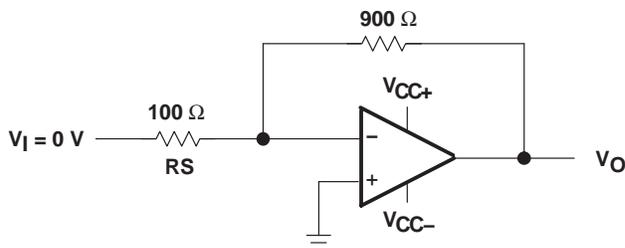


Figure 2. Noise-Test Circuit

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
LM2902KAVQDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM2902KAVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM
LM2902KVQDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM2902KVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM
LM2902QDRQ1	ACTIVE	SOIC	D	14	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
LM2902QPWRQ1	ACTIVE	TSSOP	PW	14	2000	TBD	CU NIPDAU	Level-1-250C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

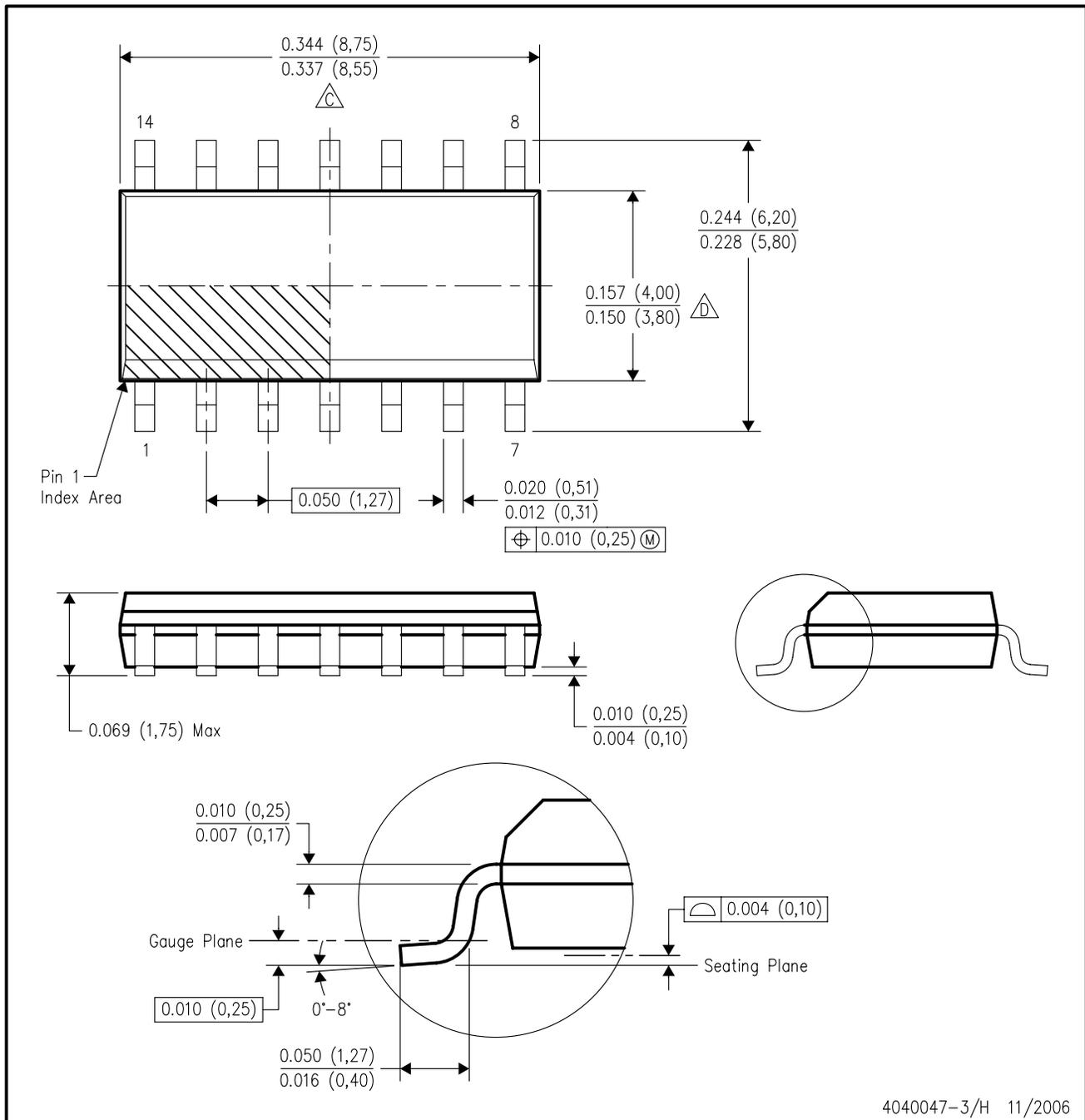
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

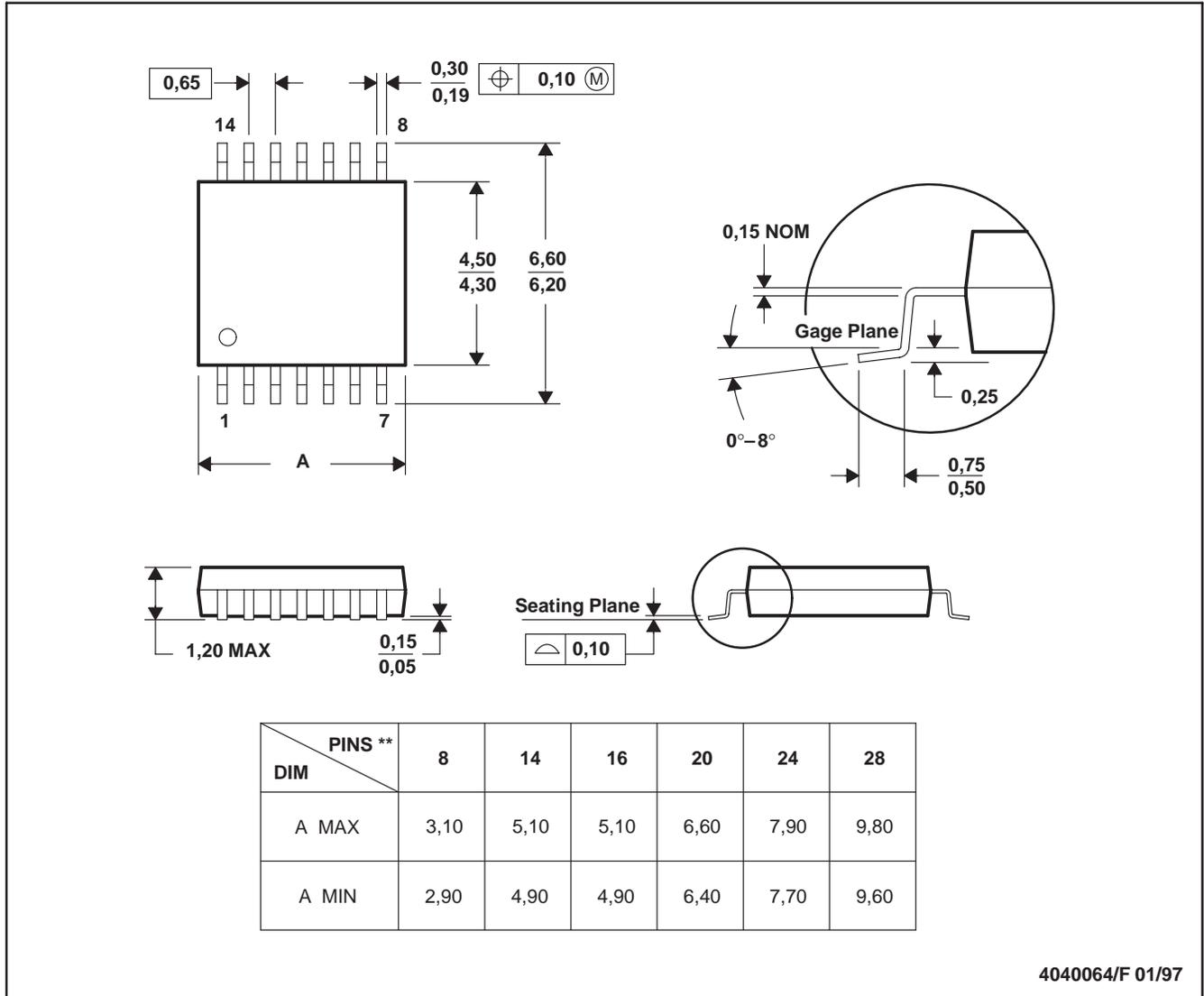


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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